



RE334-LF

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Hot air leveling (HAL-leadfree)
- Surface with component print and soldering stop mask
- Hole spacing 2.54 x 2.54 mm
- 32 x 53 soldering pads 2.00 x 2.00 mm
- Hole diameter 1.00 mm
- Connector 32/64/96-channel DIN 41612 type C
- The component side is totally laminated by copper
- No conducting connection to the component side by etched free holes
- If the copper coating is grounded, the electrical components are optimally shielded against the solder side
- By this HF, digital and analog circuits can be built up with high reliability
- Size 100 x 160 mm